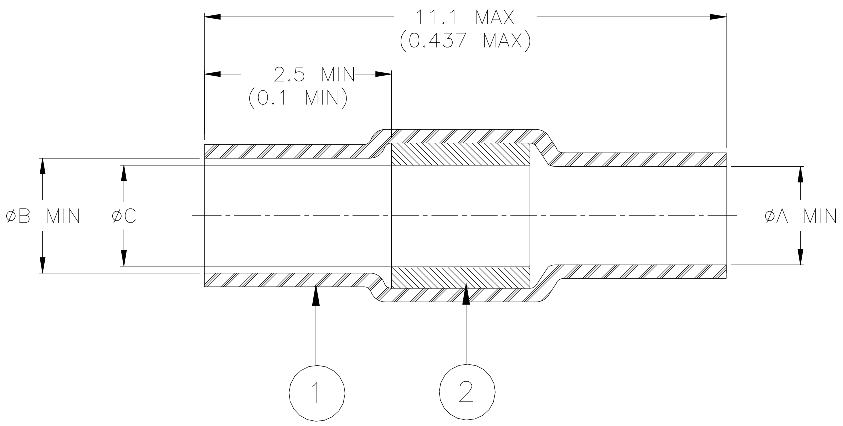
CUSTOMER DRAWING



Product Name	Product Dimensions		
	øA[1] min	øB[1] min	øC[2]
D-110-6301	1.9 (0.075)	2.65 (0.105)	2.52±0.05 (0.010±0.002)
D-110-6302	2.8 (0.110)	3.70 (0.145)	3.15±0.05 (0.124±0.002)
D-110-6303	4.6 (0.180)	5.08 (0.200)	5.06±0.1 (0.200±0.004)
D-110-6304	6.0 (0.235)	6.35 (0.250)	6.5±0.1 (0.255±0.004)
D-110-6305	7.1 (0.280)	7.62 (0.300)	7.6±0.1 (0.300±0.004)
D-110-6306	9.0 (0.355)	10.40 (0.410)	10.20±0.08 (0.402±0.003)

1) As received minimum: Insulation diameter for wires entering this end must be less than this value.
2) Solder preform diameter: Combined conductor diameter must be less than this value.

MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:
   SOLDER: TYPE Sn63 per ANSI-J-STD-006.
   FLUX: TYPE ROL0 per ANSI-J-STD-004.

APPLICATION

1. This part is designed for use in splicing wires rated for at least 125°C, having tin plated conductors.
2. When installed in accordance with TE Connectivity/Raychem Process Standard RCPS-100-70, parts will meet performance requirements of TE Connectivity/Raychem Specification RT-1404 for non-sealed splices.
3. Temperature rating: -55°C to +150°C.
4. Pre-tinning wires larger than 20AWG (use Sn63 solder) will decrease installation time and increase usable CMA

Raychem
THERMOFIT
DEVICES

TITLE:
SOLDERSLEEVE DEVICE*

Unless otherwise specified dimensions are in millimeters.
[Inches dimensions are shown in brackets]

DOCUMENT NO.:
D-110-630X

TOLERANCES:
0.00 N/A
0.0 N/A
0 N/A

ANGLES: N/A

ROUGHNESS IN MICRON

TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.

REV: 2

DATE: 24-Jul-2020

DRAWN BY: M. FORONDA

DATE: 20-June-2000

ECO: ECO-20-010292

SCALE: NTS

SIZE: A

SHEET: 1 of 1